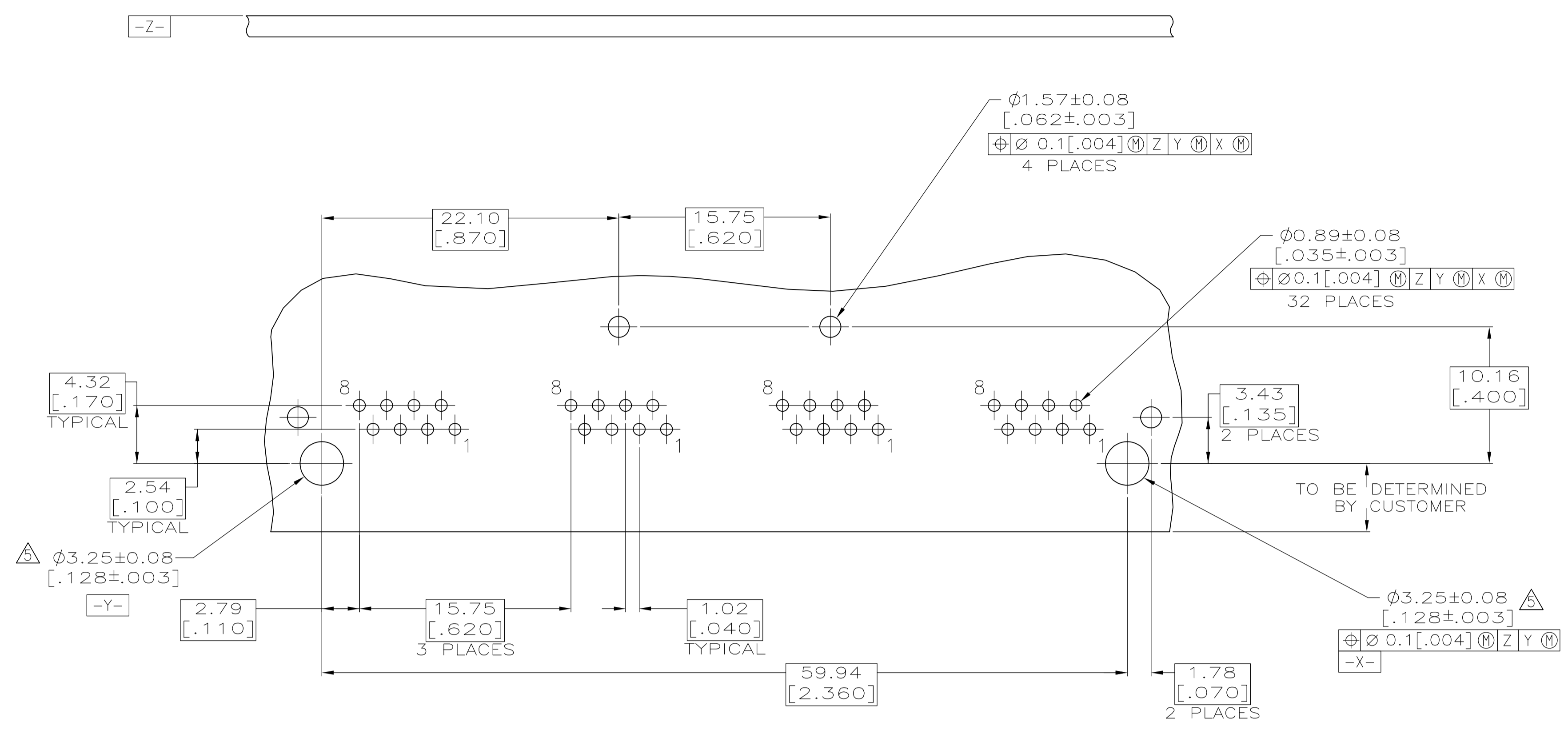
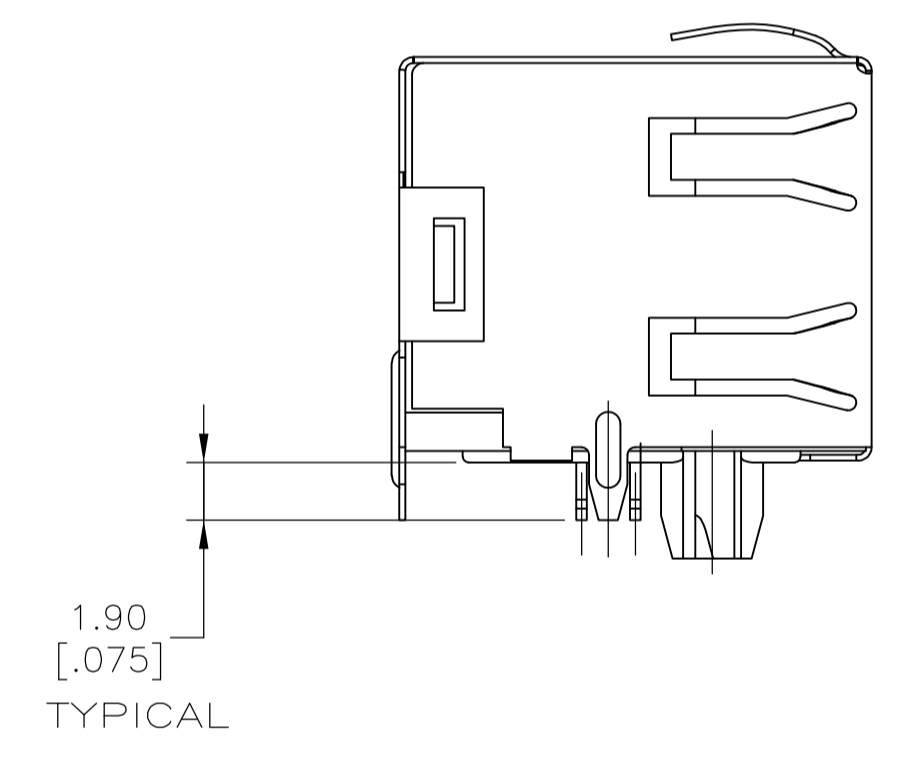
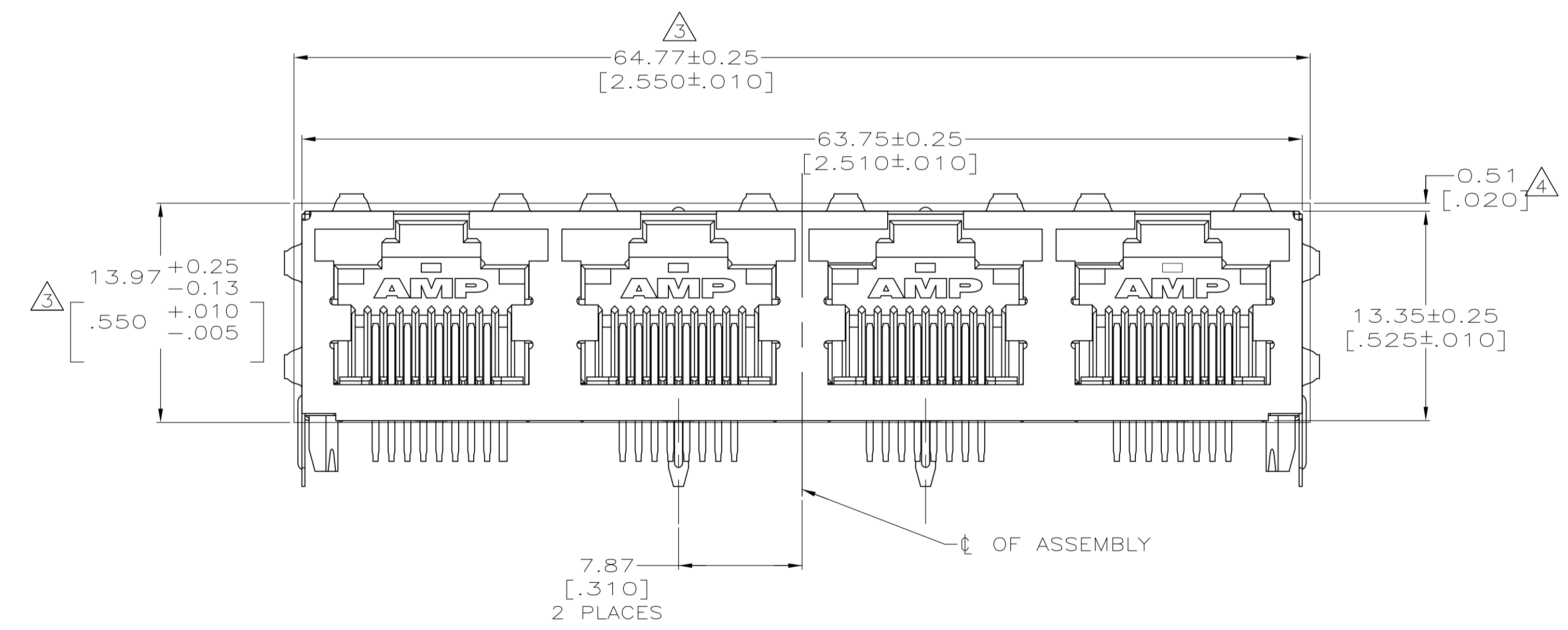
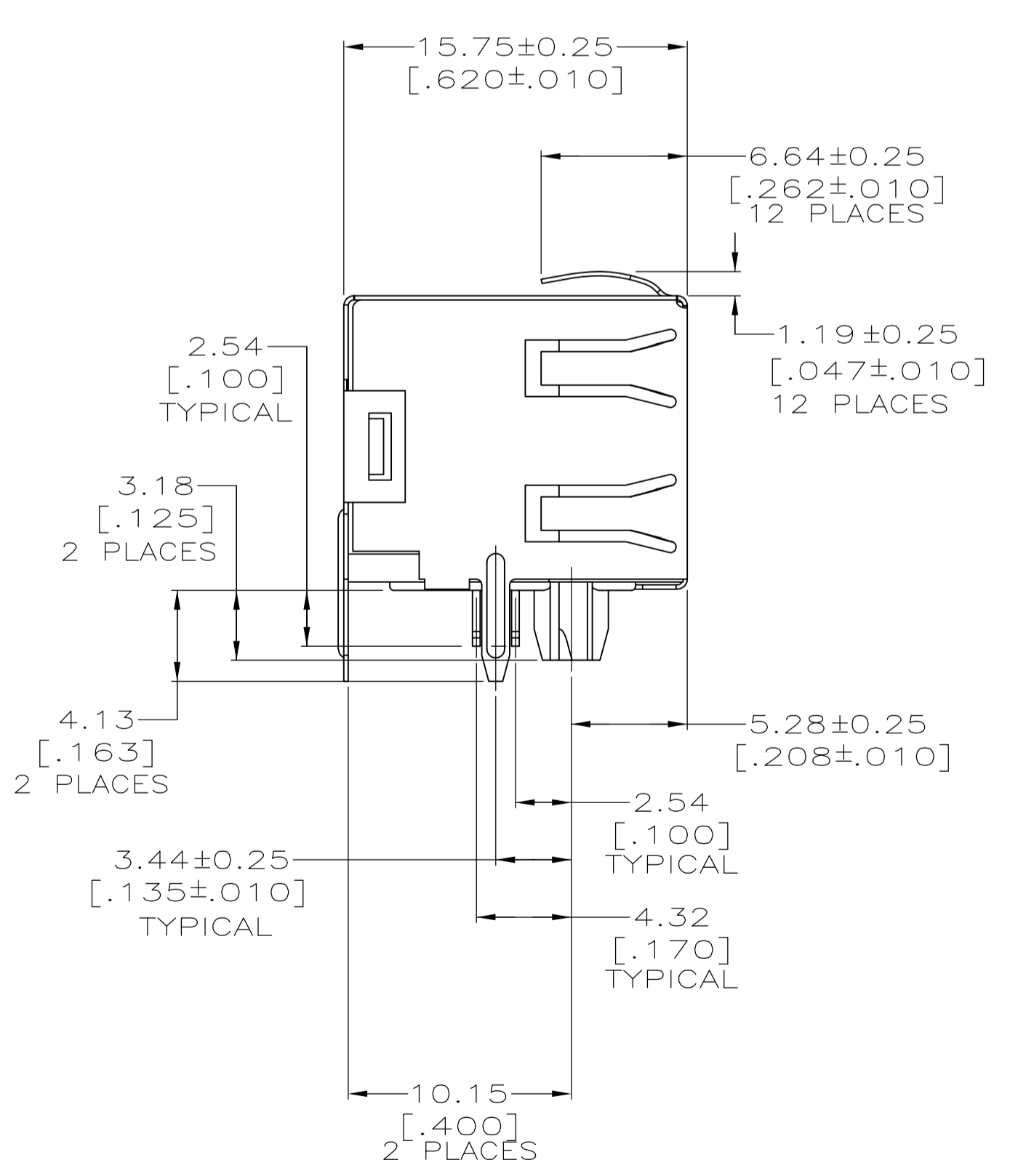


LOC	DIST	REVISIONS						
AA	22	REV	PER	ECO	DATE	BY	CHK	
		B1	REV	PER	ECO-14-011533	29JUL2014	CW	SH
		B3	PER	ECO-15-016408		28AUG15	AD	SH



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



ONLY FOR 5406544-3

- ⚠ MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27μm [.000050] MINIMUM THICK NICKEL.
SHIELD - .196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27μm[.0000500] MIN NICKEL WITH 2.03 μm[.000080] -3.81 μm [.000150] POST DIP TION ON PCB GROUND TABS.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ⚠ SUGGESTED PANEL OPENING DIMENSIONS.
- ⚠ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- ⚠ PLEASE ENSURE THE HOLE IS FULL CIRCLE SHAPE
- ⚠ CAPABLE WITH LEAD FREE IR-REFLOW SOLDERING PROCESS.

DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPROVED:		NAME:	
mm	[INCHES]	0 PL	±	APVD	DATE	NAME	DATE
		1 PL	±	J. WESTMAN	16JUN2005	S. FLICKINGER	16JUN2005
		2 PL	±				
		3 PL	±				
		4 PL	±				
		ANGLES	±				

THIS DRAWING IS A CONTROLLED DOCUMENT.	DIN J. ALCORTA - 16JUN2005	DOCK 5			
	CHK J. WESTMAN	16JUN2005			
	APVD S. FLICKINGER	16JUN2005			
	NAME	INVERTED MOD JACK ASSEMBLY, 1x4, SHIELDED, PANEL GROUND			
	PRODUCT SPEC	108-1163-4			
	APPLICATION SPEC	114-2154			
MATERIAL	FINISH	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
⚠	-	A1	00779	5406544	-
		WEIGHT			
		CUSTOMER DRAWING	SCALE	SHEET	REV
			4:1	1 OF 1	B3